

# Abraham Gonzalez

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## Education

**Ph.D. — Electrical Engineering and Computer Science** Aug. 2018 - Now  
University of California, Berkeley

**Bachelors of Science — Electrical Engineering** Aug. 2014 - May 2018  
The University of Texas at Austin  
GPA - Overall 3.98/4.00 Major 3.98/4.00

## Experience

**ADEPT Lab Ph.D. Student** Aug. 2018 - Now  
ADEPT Lab — Berkeley, CA

- Research focus: Microarchitecture, Warehouse-scale computing, Architecture tooling.
- Main developer of the Chipyard SoC framework and FireSim FPGA-accelerated simulation platform.
- Developer of BOOM, a Linux booting open-source RISC-V out-of-order core.

**Data Analytics Student Researcher** Jun. 2021 - Now  
Google — Berkeley, CA

- Research intern working on data analytics acceleration.

**BEAGLE: Heterogeneous Multi-Core Multi-Accelerator Chip in Intel 22FFL** May 2019 - Sep. 2021  
ADEPT Lab — Berkeley, CA

- Led tapeout as well as integrated IP into new Chipyard SoC framework.
- Coordinated interaction between Berkeley and Intel during physical design process.
- Tested chip using newly created bringup collateral for BEAGLE-like designs.

**CPU Design Intern** Jun. 2020 - Aug. 2020  
Apple — Berkeley, CA

- Performed research and development for CPU infrastructure team.

**Scalable Performance CPU Development Group Intern** May 2018 - Aug. 2018  
Intel — Austin, TX

- Worked on debugging tools for microcontroller integration team.
- Helped setup infrastructure between firmware team and microcontroller integration team to speed up work.

**Microsystems Technology Lab Intern** Jun. 2017 - Aug. 2017  
Massachusetts Institute of Technology — Cambridge, MA

- Researched variations in electroplating growth in redistribution layers under the supervision of Dr. Boning.
- Designed various neural networks and machine learning models for electroplating growth using Tensorflow.
- Presented final research poster summarizing work (2nd place at SHPE Conference 2017) and participated in multiple MITSRP workshops.

**Office Shared Graphics Explore Intern** May 2016 - Aug. 2016  
Microsoft — Redmond, WA

- Created and added new features within the Office Ink suite using C++.
- Created physical network of Arduino microcontrollers for OneWeek Hack-a-thon that once connected to each other sent a unique code to main server (HTTP requests).

**UIM Driver Intern** May 2015 - Aug. 2015  
Qualcomm — San Diego, CA

- Designed software framework for smartcard interaction in C++/CLI and C++.
- Integrated framework into .NET application managing smartcards via CCID by utilizing APDU transmission and logging; file system viewing; file data parsing and manipulation; and smartcard reader management.

## Skills

**Hardware Experience:** RISC-V, Chisel/Verilog/VHDL, ARM Assembly

**Software Experience:** C/C++/C#/CLI, Python/Bash, Make, Git, TensorFlow/PyTorch

**Other Experience:** AWS EC2, Xilinx FPGAs, Cadence Physical Design tooling

## Professional Leadership and Membership

Member of LAGSES (Fall 2018-Now)

Vice President (Spr. 2018), Corres. Secretary (Fall 2017), and member (Spr. 2016-Now) of HKN Honor Society

Academic Director (Fall 2016-Fall 2017), and member (Fall 2014-Now) of Society of Hispanic Professional Engineers

## Accomplishments

**UC Berkeley:** Analog Devices Outstanding Designer (Spr. 2020), Berkeley Fellowship (Fall 2018), EECS Excellence Award (Fall 2018), GEM Fellowship (Spr. 2018)

**UT Austin:** Highest Honors (Spr. 2017), Distinguished College Scholar (Spr. 2017/2018), College Scholar (Spr. 2016), R. Rocca (Fall 2017), V. L. Hand Endowed (Fall 2016), and TI Diversity Scholarship (Fall 2015)